

# N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V}$

#### **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

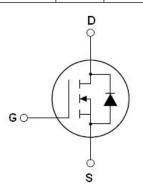
#### **Features**

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

#### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

V <sub>DS min@Tjmax</sub>	710	V
R <sub>DS(ON)TYP</sub>	165	mΩ
ID	18	Α
Qg	30	nC



Schematic diagram

♦ Intrinsic fast-recovery body diode

## **Package Marking And Ordering Information**

Device	Device Package	Marking
NCE65NF190K	TO-252	NCE65NF190K



TO-252

Table 1. Absolute Maximum Ratings (T<sub>C</sub>=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	VDS	650	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	18	А
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	12.6	А
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	54	А
Maximum Power Dissipation(Tc=25°C)	P <sub>D</sub>	194	W
Derate above 25°C		1.29	W/°C
Avalanche current <sup>(Note 1)</sup>	I <sub>AS</sub>	4	А
Drain Source voltage slope, V <sub>DS</sub> ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, V <sub>DS</sub> ≤480 V,I <sub>SD</sub> <i<sub>D</i<sub>	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55+175	°C

<sup>\*</sup> limited by maximum junction temperature



#### **Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	0.77	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

 Table 3. Electrical Characteristics (TA=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states	'			•	•	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V	V <sub>GS</sub> =0V		10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			300	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	3.5	4.2	5.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =9A		165	190	mΩ
Dynamic Characteristics						
Input Capacitance	C <sub>lss</sub>	.,		1550	1950	pF
Output Capacitance	Coss	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V,		60		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz		5		pF
Total Gate Charge	Qg			30		nC
Gate-Source Charge	Qgs	V <sub>DS</sub> =480V,I <sub>D</sub> =9A,		12.5		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V		11		nC
Gate plateau voltage	Vgp			7.5		V
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		1.5		Ω
Switching times	•					
Turn-on Delay Time	t <sub>d(on)</sub>			43		nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}=380V, I_{D}=9A,$		17		nS
Turn-Off Delay Time	$t_{d(off)}$	$R_G=1.7\Omega, V_{GS}=10V$		94		nS
Turn-Off Fall Time	t <sub>f</sub>			26		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T 0500			18	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			54	Α
Forward On Voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =18A,V <sub>GS</sub> =0V		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T: 05°0 L 0A		125		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I <sub>F</sub> =9A,		0.51		uC
Peak Reverse Recovery Current	I <sub>rrm</sub>	di/dt=100A/μs		8.2		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25  $^{\circ}\text{C}$  ,VDD=50V,VG=10V, RG=25 $\Omega$ 



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

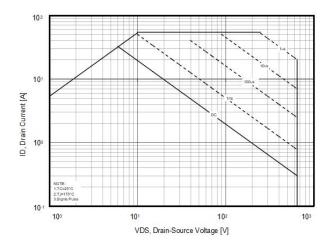


Figure 3. Transfer characteristics

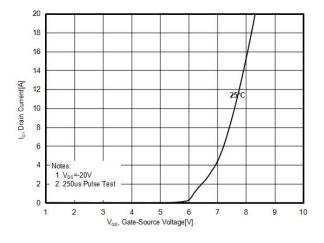


Figure 5. R<sub>DS(ON)</sub> vs Junction Temperature

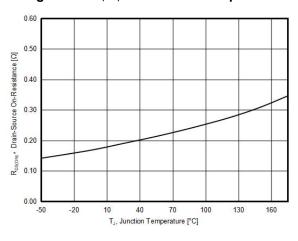


Figure 2. Capacitance

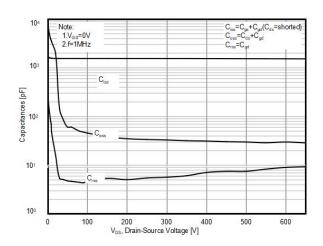


Figure 4. Output characteristics

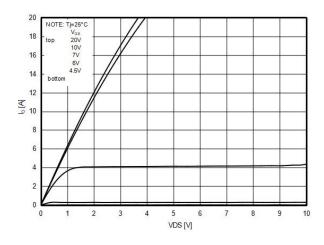


Figure 6. BV<sub>DSS</sub> vs Junction Temperature

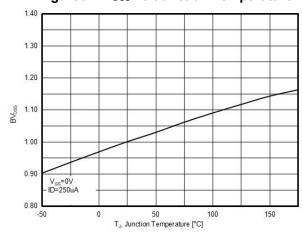




Figure 7. Maximum ID vs Junction Temperature

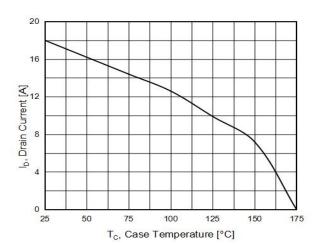


Figure8. Gate charge waveforms

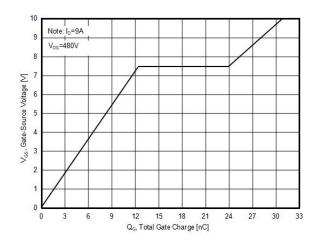


Figure 9. Static drain-source on resistance

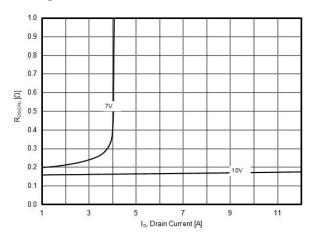
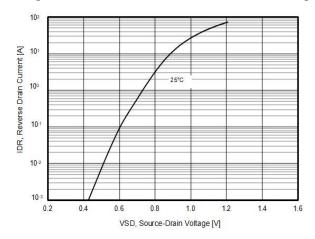


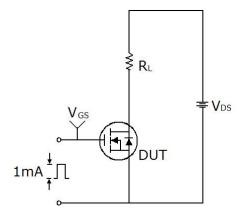
Figure 10. Source-Drain Diode Forward Voltage

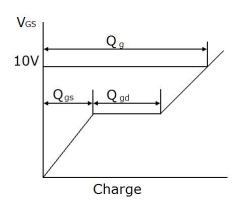




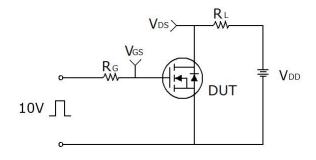
## **Test circuit**

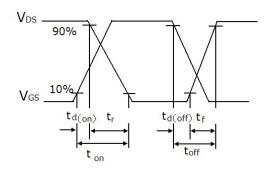
#### 1) Gate charge test circuit & Waveform



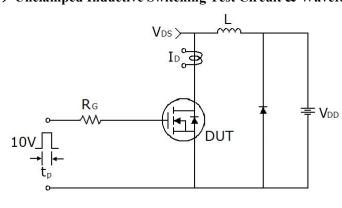


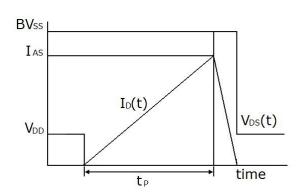
## 2) Switch Time Test Circuit:





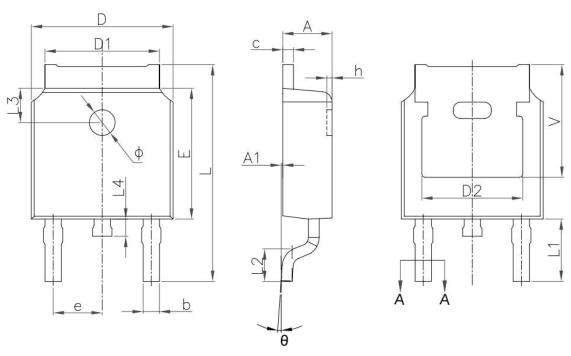
## 3) Unclamped Inductive Switching Test Circuit & Waveforms







# **TO-252-E Package Information**



Symbol	Dimensions	Dimensions In Millimeters		s In Inches	
	Min.	Max.	Min.	Max.	
А	2.20	2.40	0.087	0.094	
A1	0.00	0.13	0.000	0.005	
b	0.66	0.86	0.026	0.033	
b1	0.73	0.79	0.029	0.031	
С	0.46	0.58	0.018	0.023	
c1	0.50	0.52	0.020	0.020	
D	6.50	6.70	0.256	0.264	
D1	5.10	5.46	0.201	0.215	
D2	4.83	3 REF	0.19REF		
Е	6.00	6.20	0.236	0.244	
е	2.19	2.39	0.086	0.094	
L	9.80	10.40	0.386	0.409	
L1	2.90	2.90 REF		REF	
L2	1.40	1.70	0.055		
L3	1.60	1.60 REF		REF	
L4	0.60	1.00	0.024	0.039	
Ф	1.10	1.30	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.00	0.30	0.000	0.012	



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